

Introduction

CPE380/CS380/EE380, Fall 2017

Hank Dietz

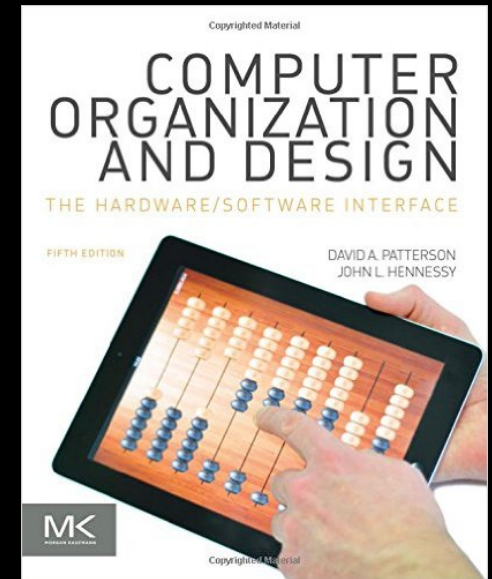
<http://aggregate.org/hankd/>

Course Overview

- You know how to write a simple program...
from **CS** courses
- You know how to build simple combinatorial
and sequential logic circuits...
from **EE** courses (especially EE280)
- **This course fills the gap between the two:**
 - So you can create the stuff in between
 - So you can better specify & use that stuff

Textbook

- The text is:
Computer Organization & Design, 5th Edition: The Hardware/Software Interface by Patterson & Hennessy
- You can use any edition from 2nd on, but we'll reference sections from the 5th
- We will not assign problems from the text
- Lots of additional materials at the course URL and presented in class...



Grading & Such

- Two in-class exams, ~20% each
- One final exam, ~30%
- Material cited from the **text**, from **lectures**, or from the **course URL**:
<http://aggregate.org/EE380/>
- Other, ~30%
(typically, homework via WWW forms)
- I try not to curve much, but might adjust %

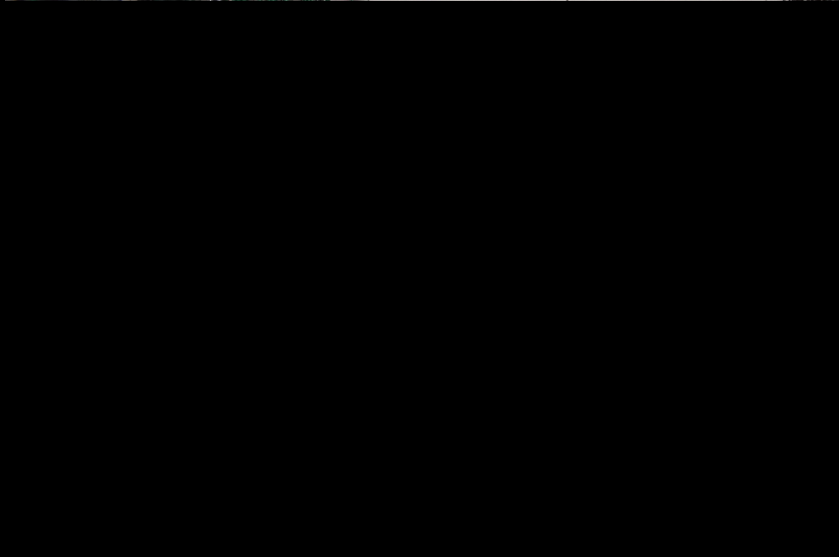
Course Content

Topic	Primary Reference	Weeks	Exam
Introduction	Book Chapter 1	1.0	0
A Simple Machine	Online (EE280 review from Book Appendix B)	2.0	0
Performance	Book Chapter 1	0.5	0
Machine Language	Book Chapter 2	1.5	1
Arithmetic	Book Chapter 3	2.0	1
Data Path & Control	Book Chapter 4	1.0	1
Pipelining	Book Chapter 4	1.5	2
Memory & I/O	Book Chapter 5	1.5	2
Parallel Processing	Book Chapter 6	1.0	2

Me (and why I'm biased)

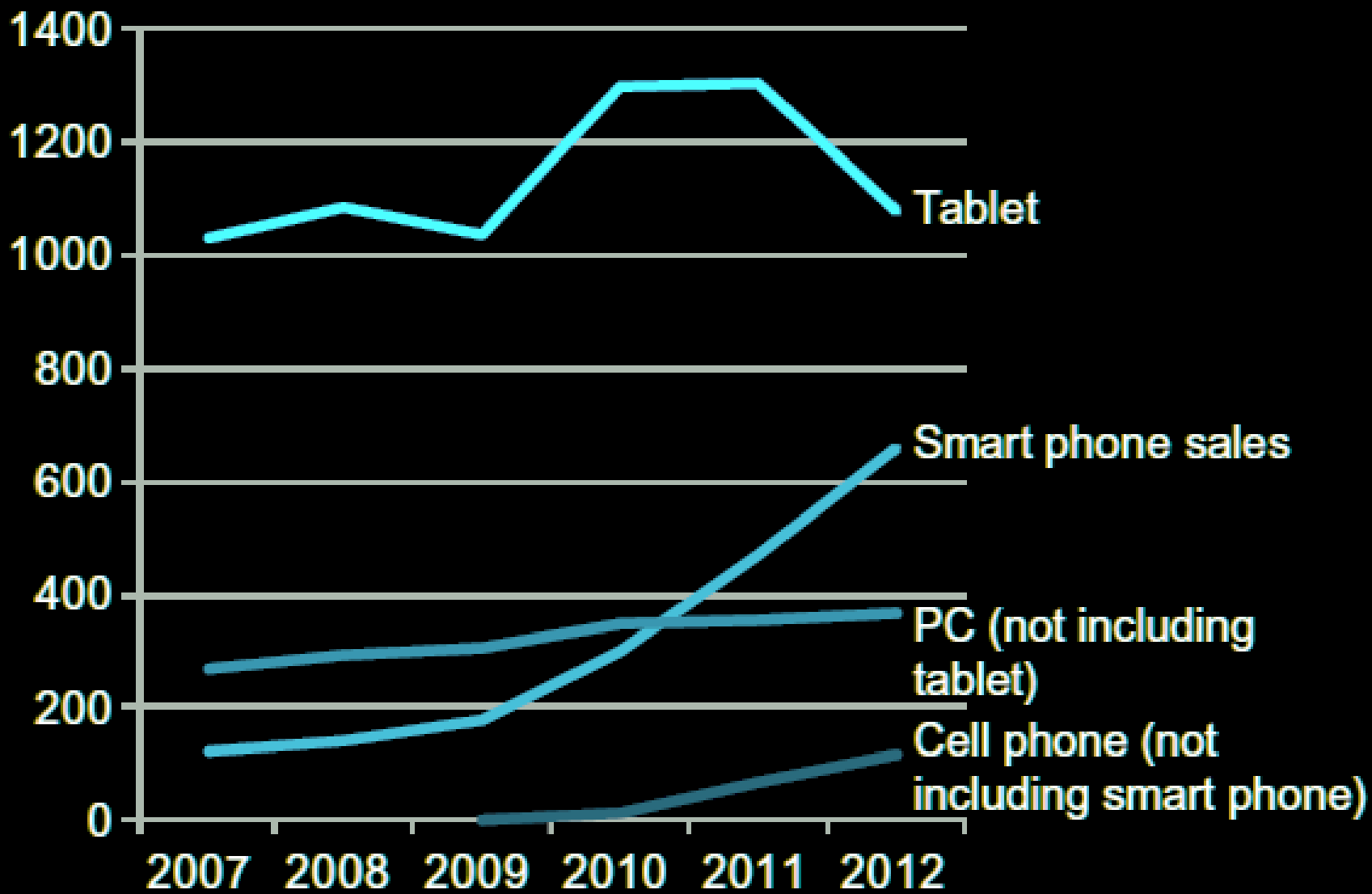
- **Hank Dietz**, ECE Professor and James F. Hardymon Chair in Networking
- Office: **203 Marksbury**
- Research in parallel compilers & architectures:
 - Built 1st Linux PC cluster supercomputer
 - Antlr, AFNs, SWAR, FNNs, MOG, ...
 - Various awards & world records for best price/performance in supercomputing
- Labs: **108 Marksbury**, 672 FPAT – I have **TOYS!**



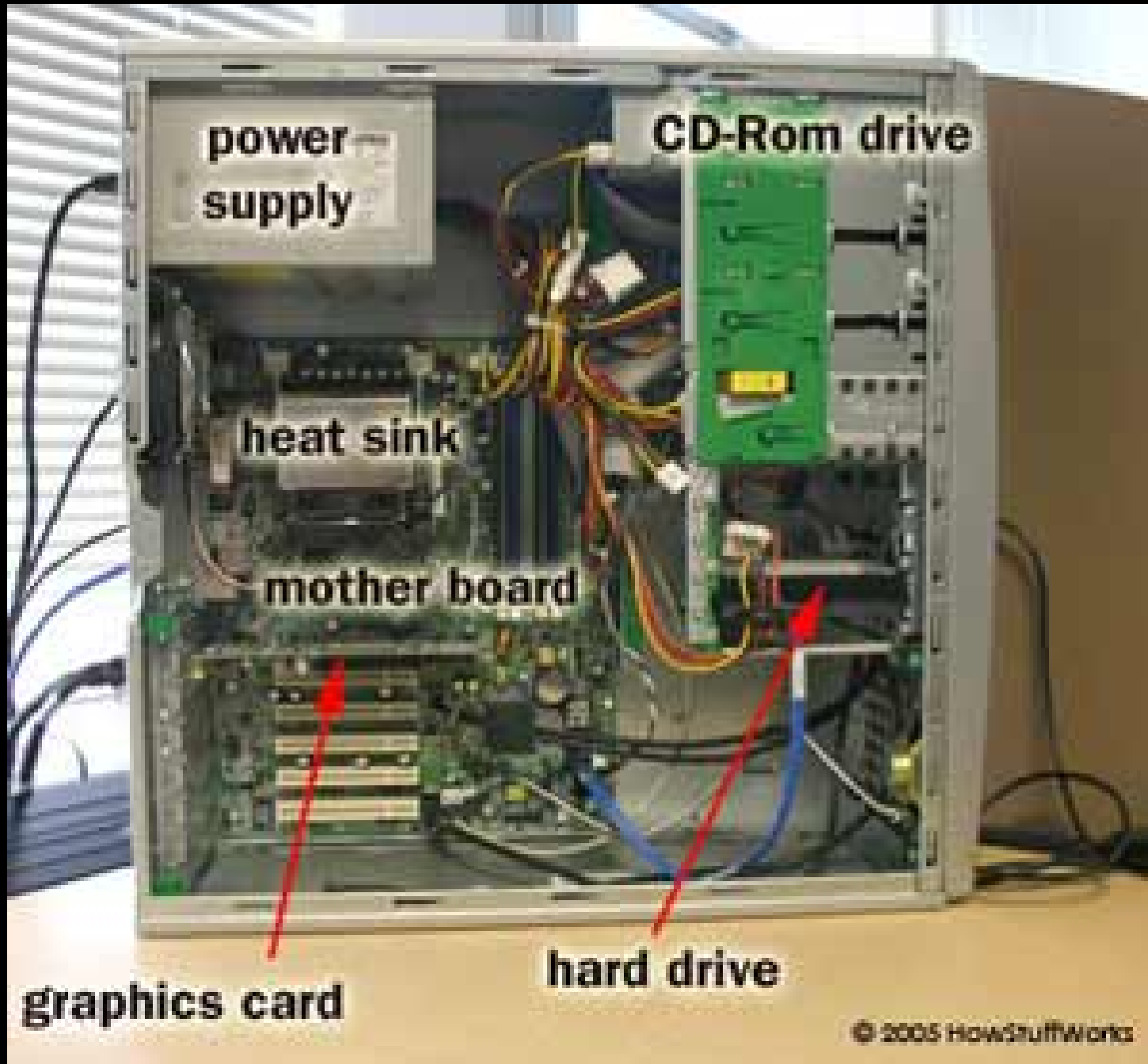


Let's Talk About Computers

- Embedded computers
- Personal Mobile Devices (PMDs)... usually “smart phones” and tablets
- Personal Computers (PCs)
- Servers
- Supercomputers
- Clusters, Farms, Grids, and Clouds (Warehouse Scale Computers – WSC, Software as a Service – SaaS)



What's Inside?



power supply

CD-Rom drive

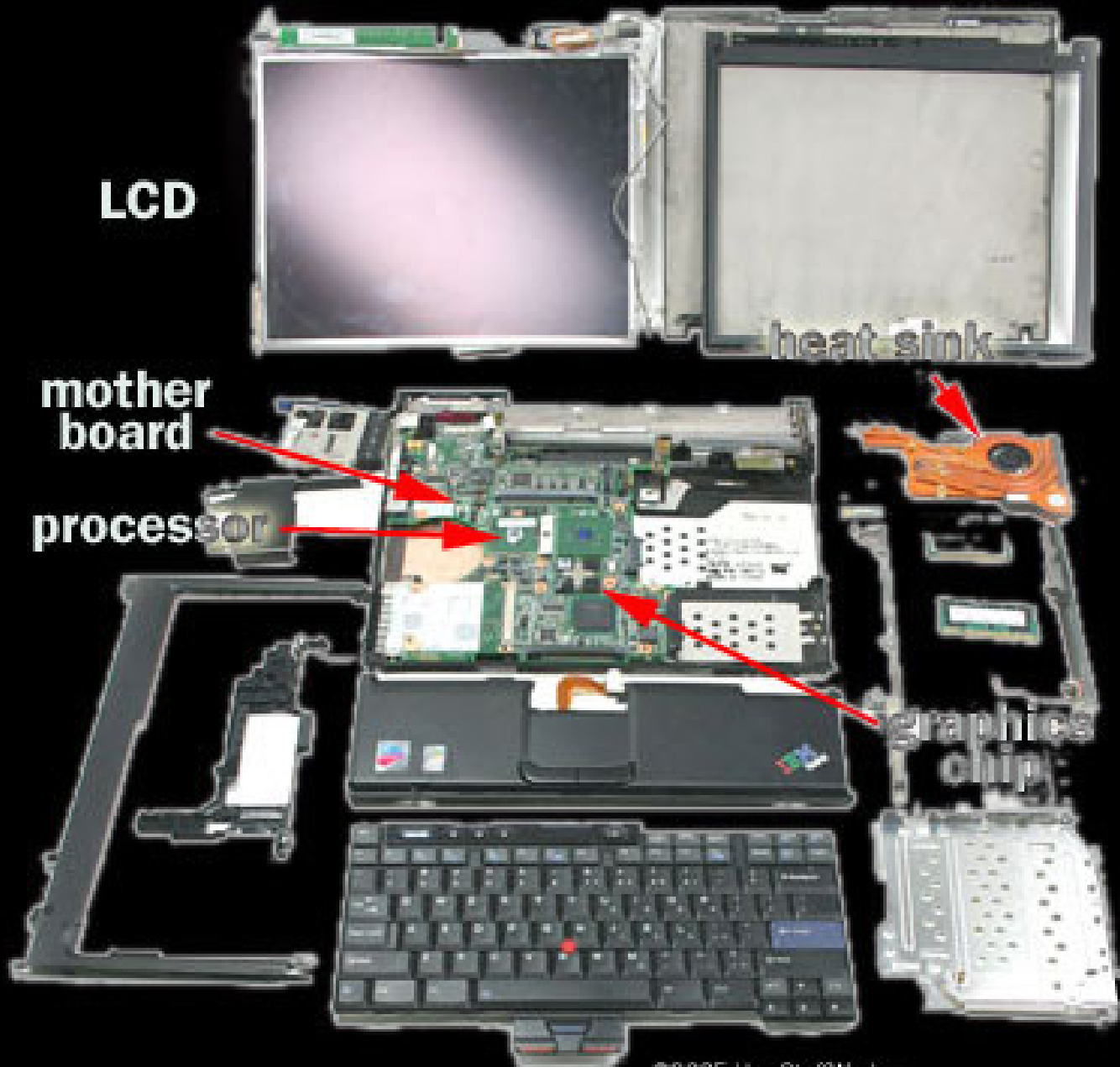
heat sink

mother board

graphics card

hard drive

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LCD

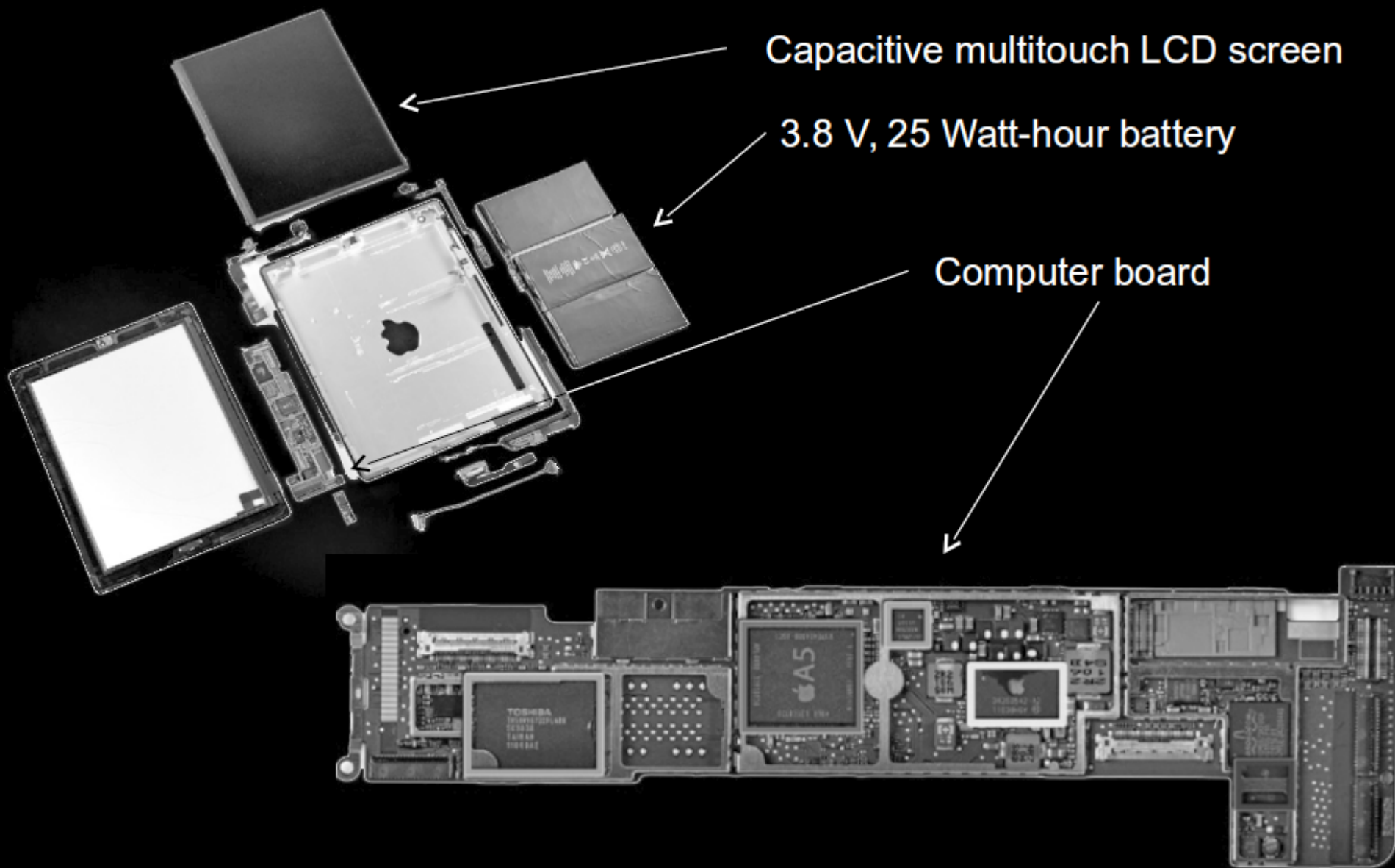
heat sink

mother board

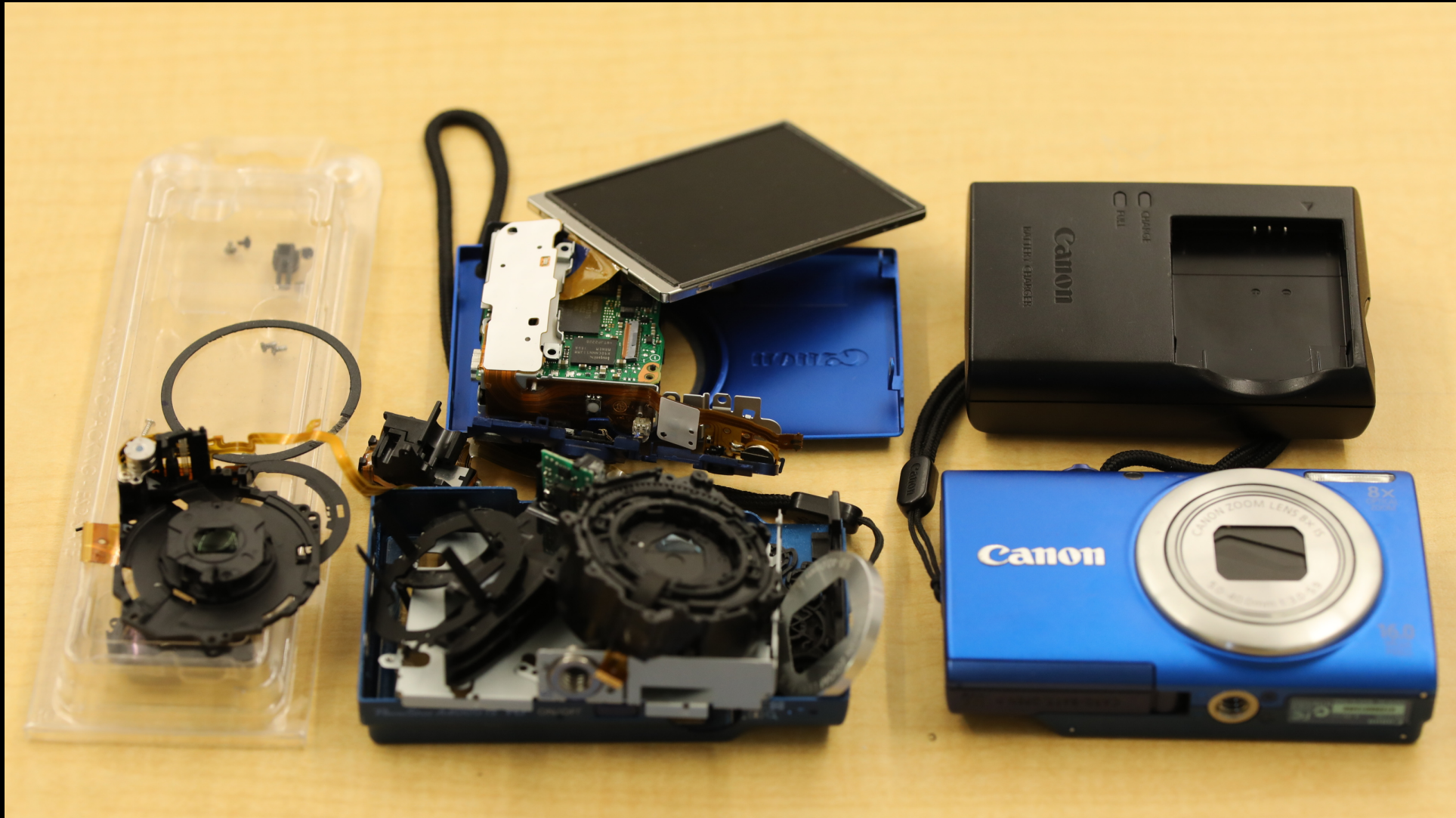
processor

graphics chip

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FlashAir

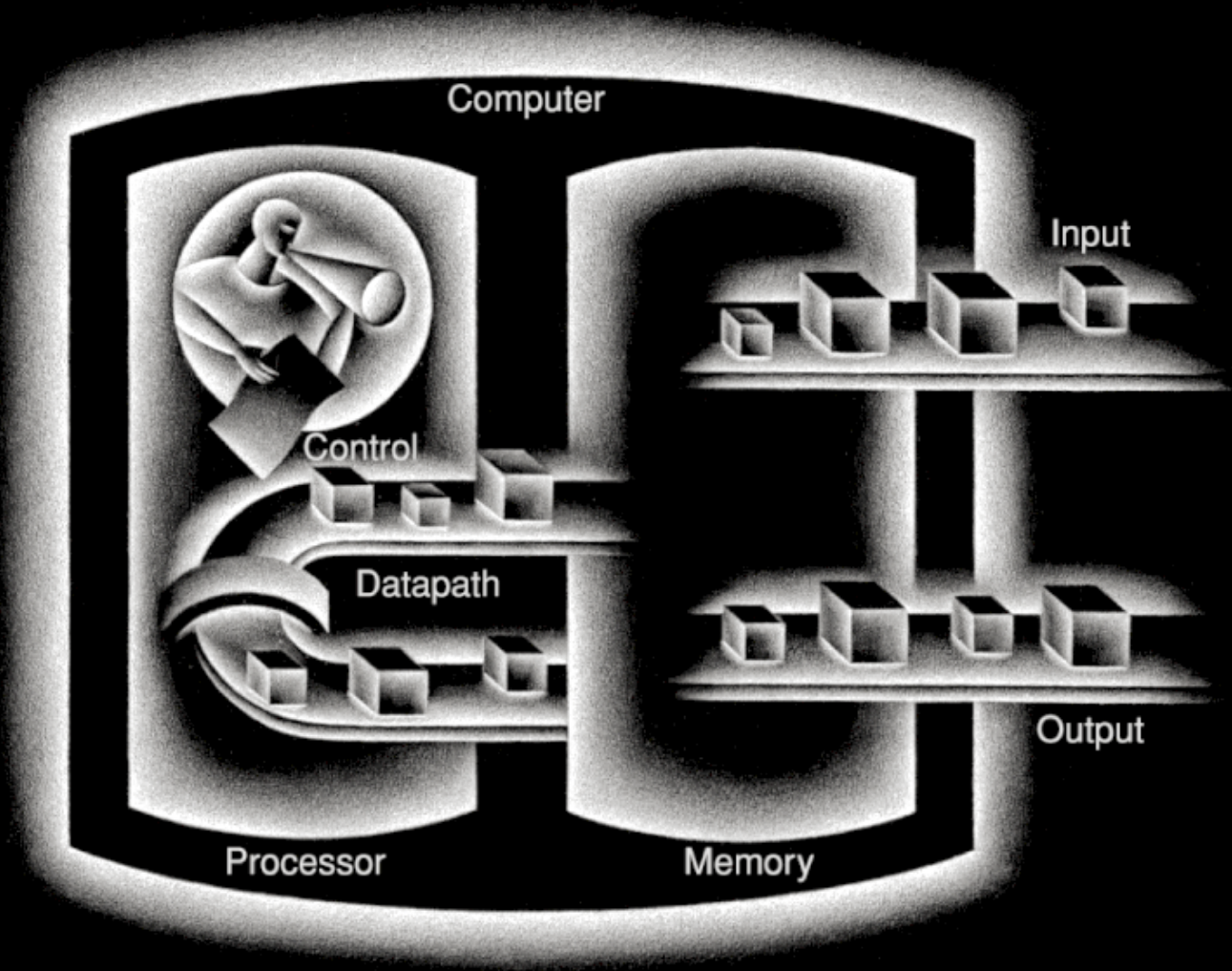
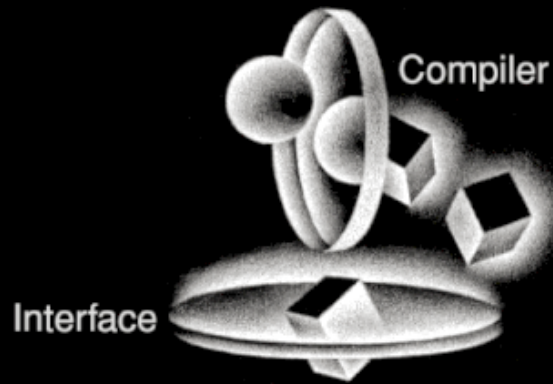
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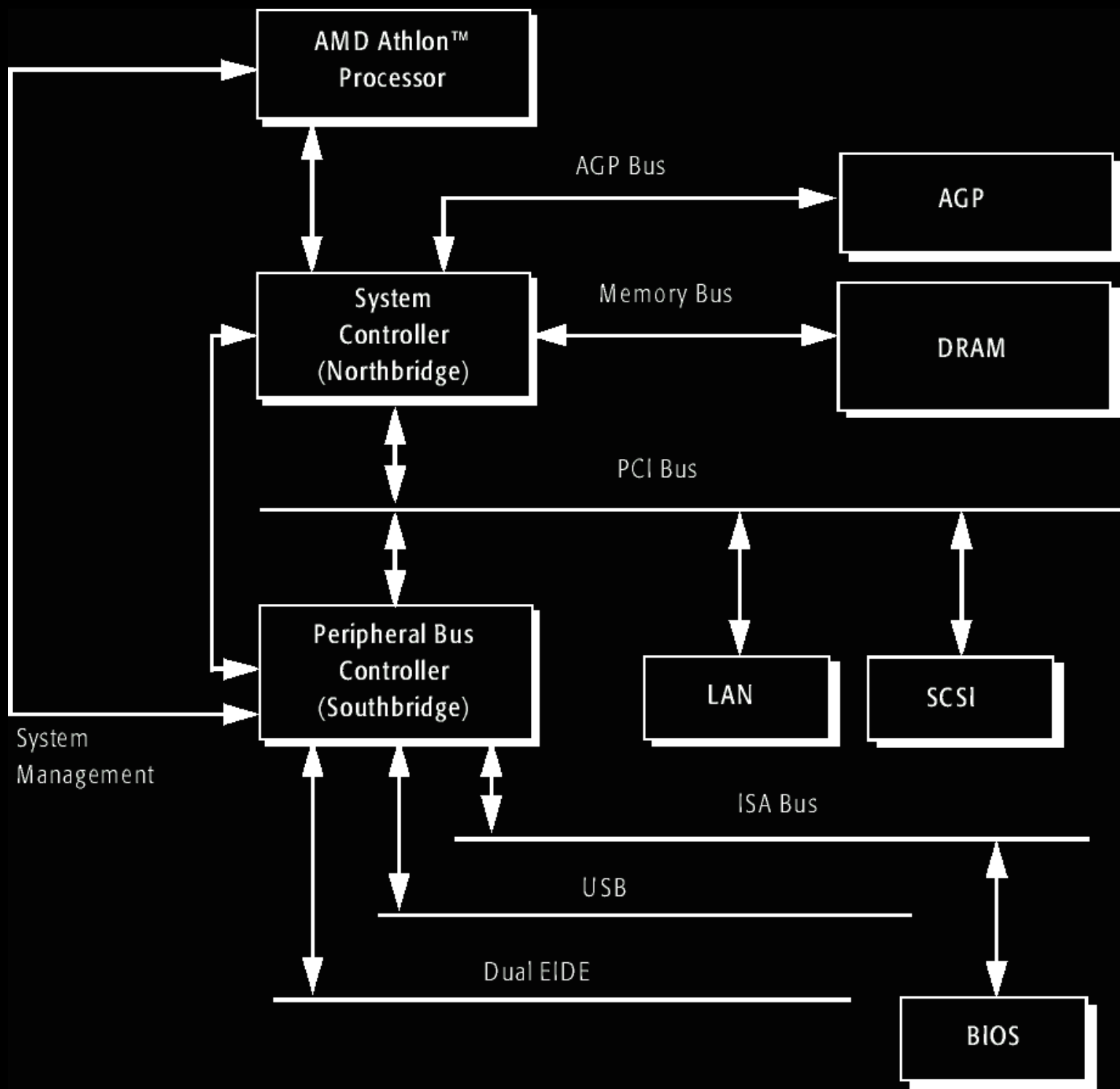


Wireless LAN

UHS-I 32 GB

TOSHIBA





Memory Terminology

- **Volatile** – power off, data fades away
- **ROM** – non-volatile Read Only Memory
- **PROM, EPROM, OTP, EEROM, Flash** – types of non-volatile programmable memory
- **RAM** – volatile Random Access Memory
 - **SRAM** – Static RAM, fast but big cells
 - **DRAM** – Dynamic RAM, slow but small cells
 - **EDO, SDRAM, DDR, RamBus** – DRAM types
- **Core** – non-volatile magnetic RAM technology
- **Registers, Cache** – fast working memories

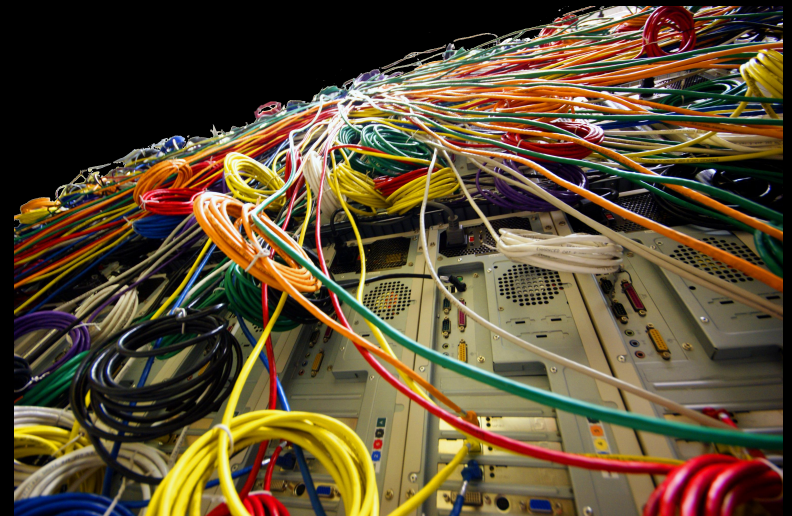
More Memory Terminology

- Punched cards
- Punched paper tape
- Tape, Magtape
- Drum
- Disks:
Floppy, Hard, Magneto-optical, CD (-R, -RW),
DVD (+/-R, +/-RW, -RAM), Blu-ray
- Flash, SSD (Solid State Disk), 3D XPoint



Network Terminology

- SAN, LAN, MAN, WAN – Area Network; System/Storage, Local, Metropolitan, Wide
- Ethernet, DSL (Digital Subscriber Line)
- USB, FireWire
- Hub, Switch, Router
- WiFi, Bluetooth, NFC
- Bandwidth, Latency



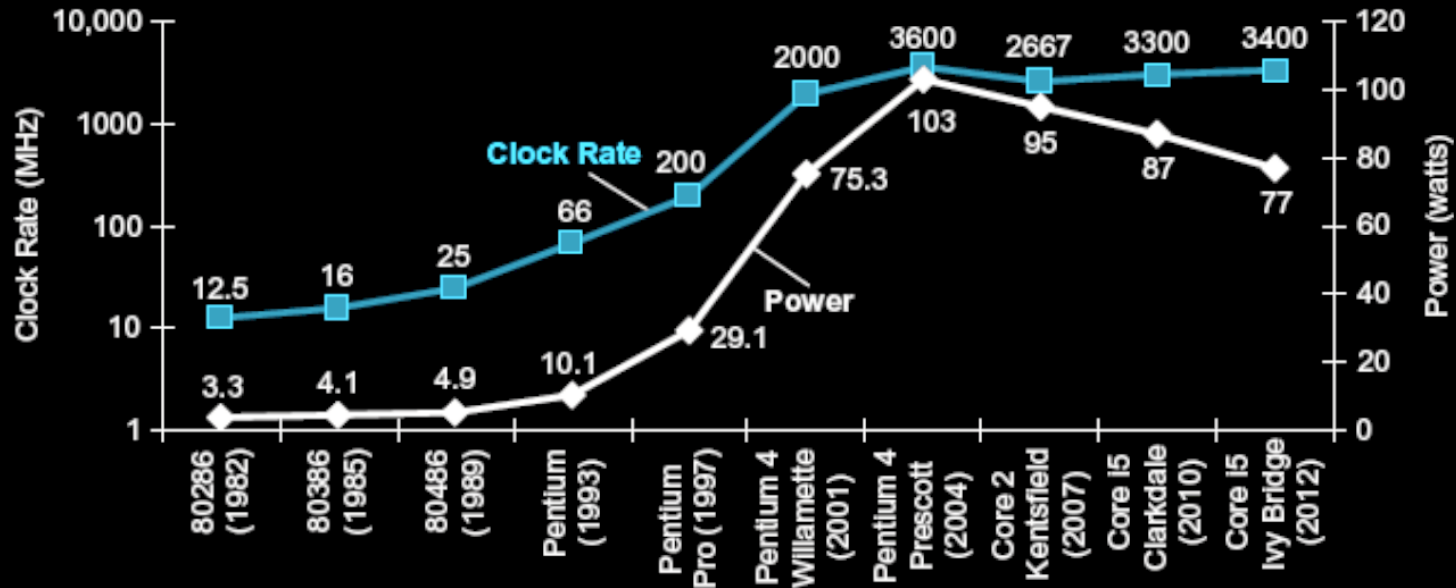
Other I/O Terminology

- Keyboard
- Mouse, Trackball, Touchscreen, Lightpen, Touchpad, etc.
- Pixel – Picture Element
- In a camera: CCD (Charge-Coupled Device), CMOS
- In a display: CRT (Cathode Ray Tube), Plasma, LCD (Liquid Crystal Display), DMD (Digital Micromirror Device, aka DLP), OLED (Organic Light Emitting Diode)

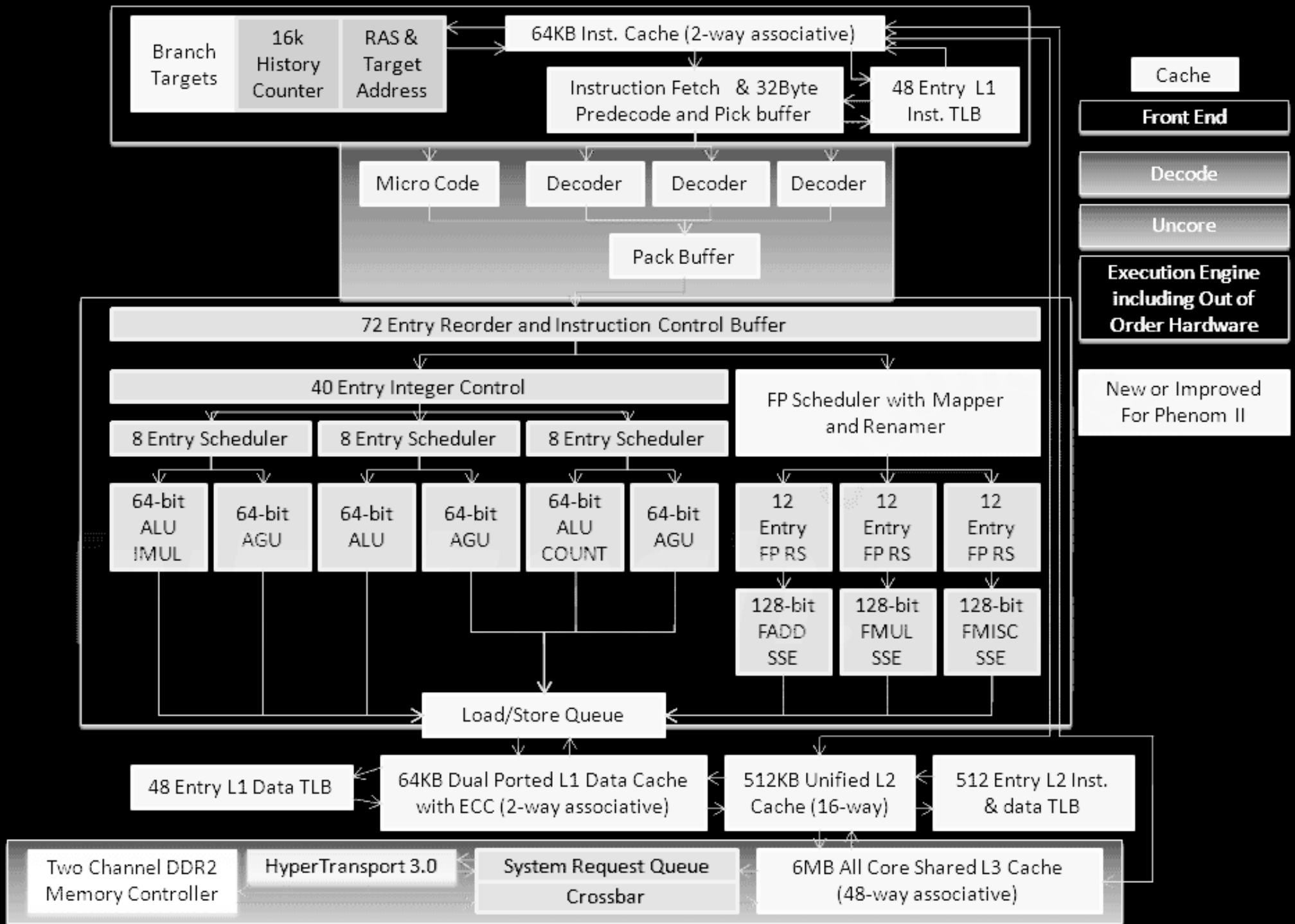
Processor Terminology

- CPU – Central Processing Unit
- PE, Core – Processing Element
- Processor – CPU or chip containing PEs
- “Computer Family” – same ISA
- IA32, x64 – ISAs based on the Intel 386
- MIPS, ARM, SPARC – other common ISAs
- DSP – Digital Signal Processor
- GPU – Graphics Processing Unit

Why Multi-Core?



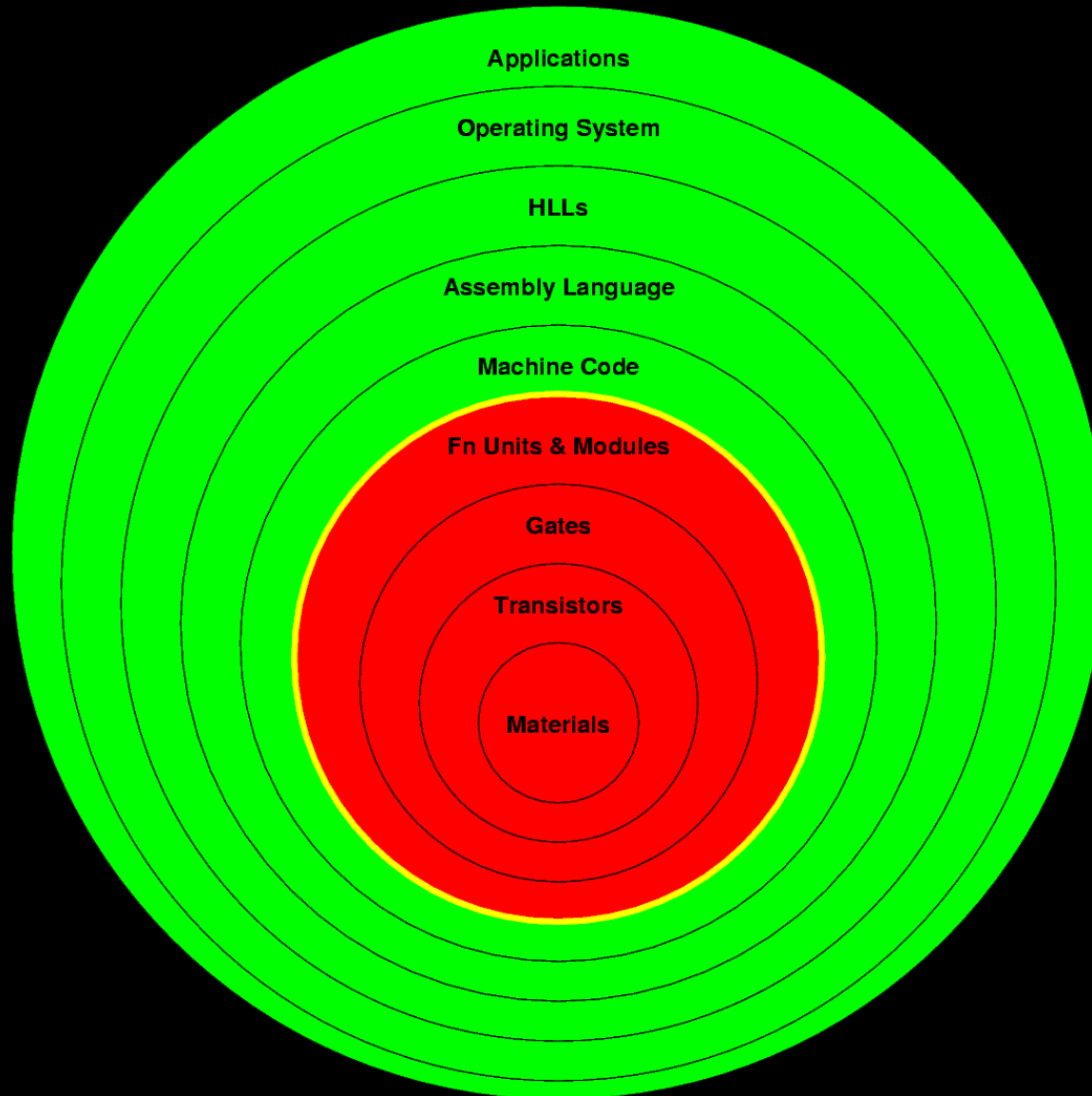
- Hit the “**power wall**”
- Lower voltage & slower clock reduce power more than performance
- Software companies changed license fees



Complexity

- Things are much more complex now
- Lots of things you use every day have **BILLIONS** of components!
- You don't live long enough to know it all

Abstraction “Onion”



Software Layers

- Applications...
- Operating Systems (OS)...
- High-Level Languages (HLLs)
Aka, High Order Languages (HOLs)
 - Designed for humans to write & read
 - Modularity
 - Abstract data types, type checking
 - Assignment statements
 - Control constructs
 - I/O statements

Instruction Set Architecture

- ISA defines HW/SW interface
- **Assembly Language**
 - Operations match hardware abilities
 - Relatively simple & limited operations
 - Mnemonic (human readable?)
- **Machine Language**
 - Bit patterns – 0s and 1s
 - Actually executed by the hardware

High-level
language
program
(in C)

```
swap(int v[], int k)
{int temp;
  temp = v[k];
  v[k] = v[k+1];
  v[k+1] = temp;
}
```

↓
Compiler

Assembly
language
program
(for MIPS)

```
swap:
  muli $2, $5, 4
  add  $2, $4, $2
  lw   $15, 0($2)
  lw   $16, 4($2)
  sw   $16, 0($2)
  sw   $15, 4($2)
  jr   $31
```

↓
Assembler

Binary machine
language
program
(for MIPS)

```
00000000101000010000000000011000
00000000000110000001100000100001
10001100011000100000000000000000
10001100111100100000000000000100
10101100111100100000000000000000
10101100011000100000000000000100
00000011111000000000000000001000
```

Hardware Layers

- Function-block organization
- Gates & Digital Logic (EE280 stuff)
- Transistors
 - Used as bi-level (saturated) devices
 - Amplifiers, not just on/off switches
- Materials & Integrated Circuits
 - Implementation of transistors, etc.
 - SSI, MSI, LSI, VLSI, ... WSI?

Who Does What?

- Instruction Set Design, by *Architect*
 - Machine & Assembly Languages
 - “**Computer Architecture**”
 - **Instruction Set Architecture** / Processor
- Computer Hardware Design, by *Engineer*
 - Logic Design & Machine Implementation
 - “**Processor Architecture**”
 - “**Computer Organization**”

How To Use Layers

- Things are too complex to “know everything”
- Need to know only layers adjacent
 - Makes design complexity reasonable
 - Makes things reusable
- Can **tunnel** to lower layers
 - For efficiency
 - For special capabilities

8 Great Ideas

- Design for Moore's Law
- Abstraction
- Make the common case fast
- Pipelining
- Parallelism
- Prediction
- Hierarchy of memories
- Dependability via redundancy



Computer Architecture Is Quickly Evolving

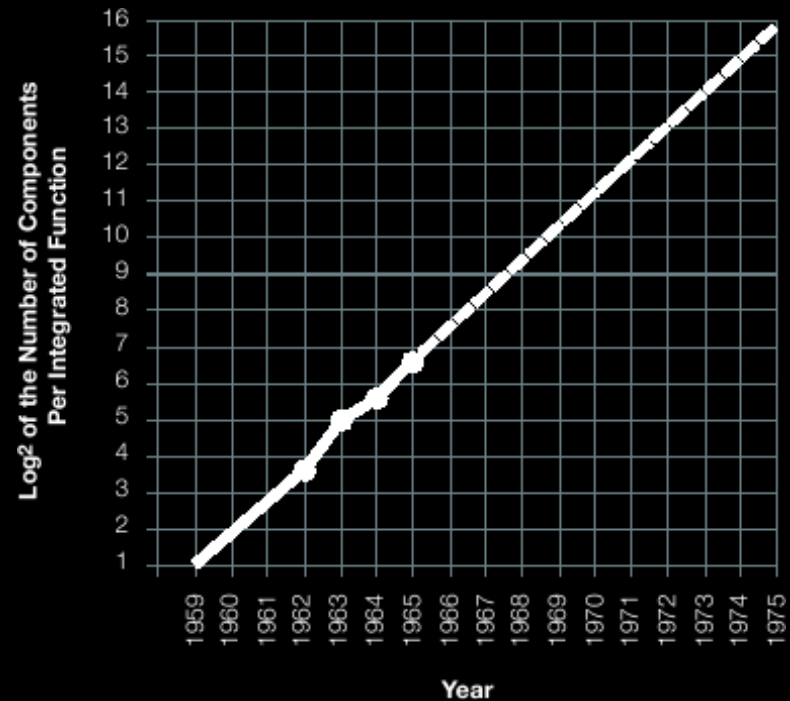
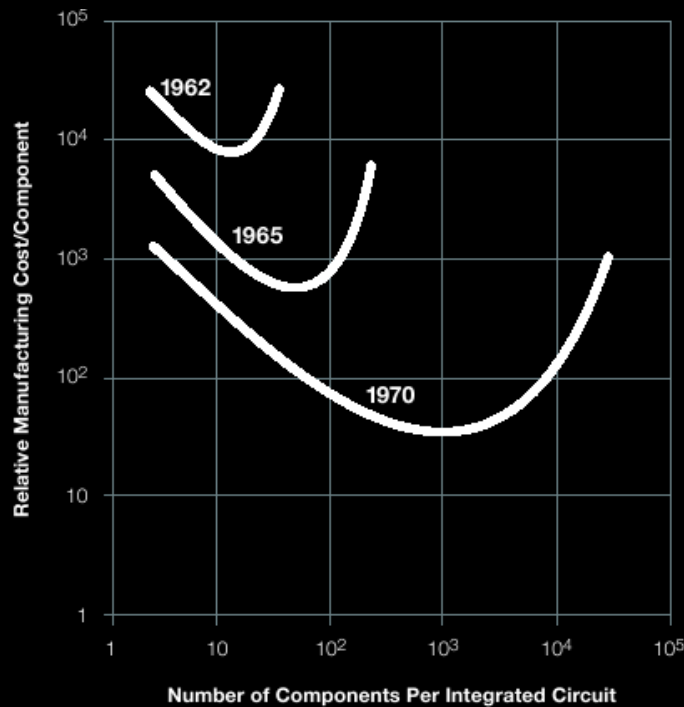
- Applications
e.g., DVDs -> MMX, Doom -> 3DNow! & SSE;
e.g., embedded systems, cell phones, etc.
- Programming Languages
e.g., C -> call stack, flat memory addresses
- Operating Systems
e.g., Windows -> execute permission
- Technology
e.g., Power density -> power management

Chip Terminology

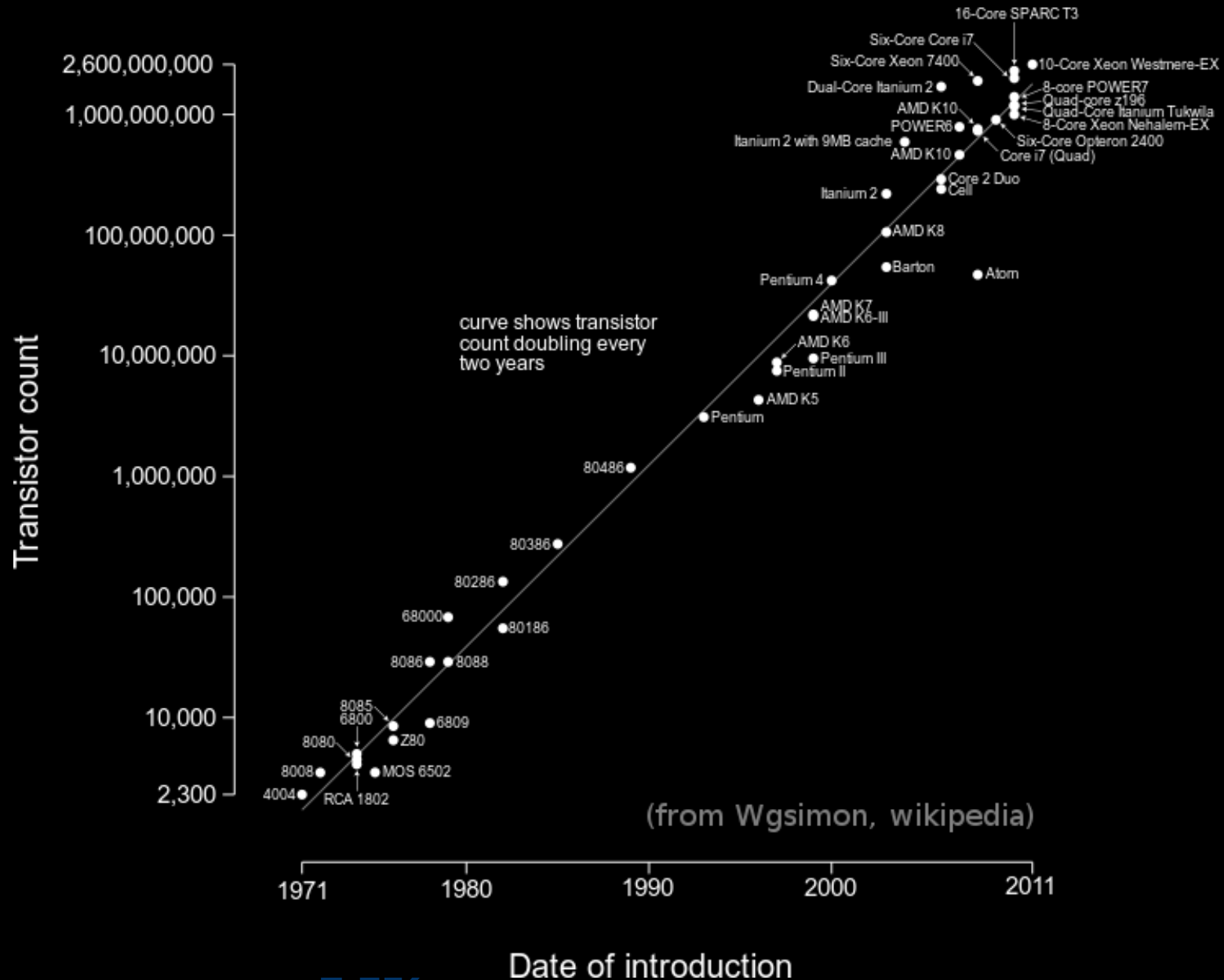
- **Silicon Ingot** – sausage-like single crystal
- **Wafer** – slice from above
- **Die** – one chip's area on a wafer
- **Chip** – a mounted die
- **Yield** – fraction that are good
- **SSI, MSI, LSI, VLSI, WSI** – Scale Integration;
Small, Medium, Large, Very Large, Wafer

Moore's Law

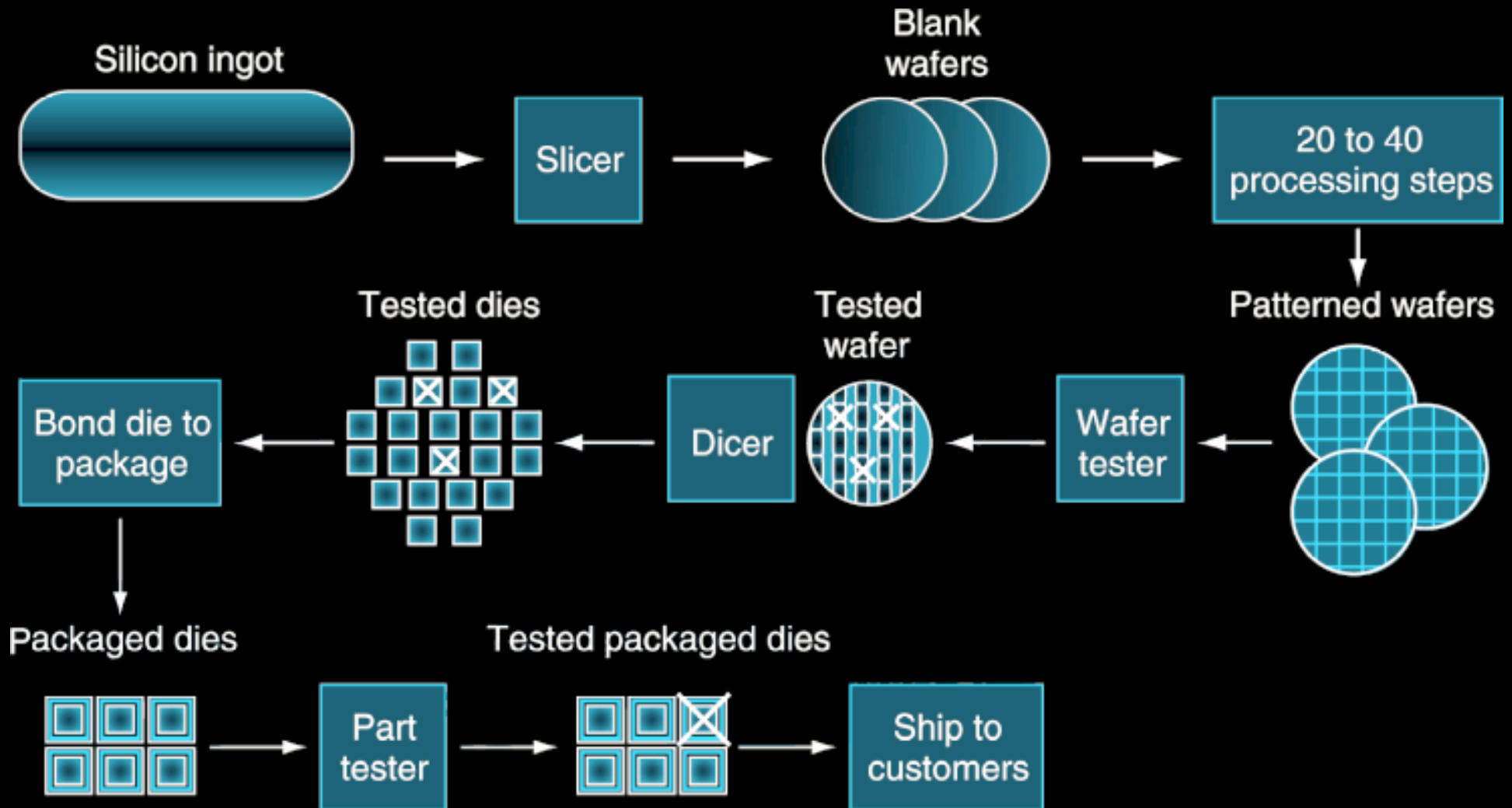
“Cramming more components onto integrated circuits,” *Electronics*, Vol. 38, No. 8, April 19, 1965.



Microprocessor Transistor Counts 1971-2011 & Moore's Law



Chip Fabrication



Chip Fabrication

$$\text{Cost per die} = \frac{\text{Cost per wafer}}{\text{Dies per wafer} \times \text{Yield}}$$

$$\text{Dies per wafer} \approx \text{Wafer area} / \text{Die area}$$

$$\text{Yield} = \frac{1}{(1 + (\text{Defects per area} \times \text{Die area} / 2))^2}$$

- Moore's Law is primarily about density, not speed
- Fab cost ~ cube of the die area

IC Costs: Dies To Chips

$$\text{IC cost} = \frac{\text{Die cost} + \text{Testing cost} + \text{Packaging cost}}{\text{Final test yield}}$$

Packaging Cost: depends on pins, heat dissipation

<i>Chip</i>	<i>Die cost</i>	<i>Package pins</i>	<i>Package type</i>	<i>cost</i>	<i>Test & Assembly</i>	<i>Total</i>
386DX	\$4	132	QFP	\$1	\$4	\$9
486DX2	\$12	168	PGA	\$11	\$12	\$35
PowerPC 601	\$53	304	QFP	\$3	\$21	\$77
HP PA 7100	\$73	504	PGA	\$35	\$16	\$124
DEC Alpha	\$149	431	PGA	\$30	\$23	\$202
SuperSPARC	\$272	293	PGA	\$20	\$34	\$326
Pentium	\$417	273	PGA	\$19	\$37	\$473

Technology Trends

	Capacity	Speed
Logic	2X in 2 years	2X in 3 years
DRAM	4X in 3 years	1.4X in 10 years
Disk	4X in 3 years	1.4X in 10 years

Different rates mean relationships change;
e.g., memory used to be faster than Add logic,
now it's ~2000X slower!

SI Terminology Of Scale

1000^1	kilo	k	1000^{-1}	milli	m
1000^2	mega	M	1000^{-2}	micro	u
1000^3	giga	G	1000^{-3}	nano	n
1000^4	tera	T	1000^{-4}	pico	p
1000^5	peta	P			

- 1000^x vs. 1024^x
- 1 **Byte (B)** is 8-10 bits (**b**), 4 bits in a **Nybble**
- Hertz (**Hz**) is frequency (vs. period)

Conclusion

- LOTS of stuff to know about...
this course just does the basic stuff around the ISA and its implementation
- New technologies & applications mean new architectures & architectural concepts
- Look at the history references on the WWW:
not to memorize who, what, when, & where,
but to *see trends...*